Special Issue

Advances in Wire-Based Metal Additive Manufacturing

Message from the Guest Editors

Wire-based metal additive manufacturing (AM) is attracting increased attention due to its ability to produce large and high-quality metallic components while minimizing material waste and reducing costs. This technique typically utilizes a heat source, such as an electric arc. laser, or electron beam, to melt the wire feedstock, enabling the creation of complex metal parts. The use of wire as feedstock offers several advantages in metal AM, including higher deposition rates, the production of fully dense materials, and the ability to manufacture a wide range of metals and alloys. The aim of this Special Issue is to showcase the latest research and technological advancements in wire-based metal AM. The scope of this Special Issue includes, but is not limited to, process optimization, material performance. the development of novel wire materials, and advancements in process monitoring and quality control. We welcome the submission of original research articles, communications, and review papers that explore these and other relevant areas.

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